



## MCS6.A

**Description:** NB-IoT / CAT M1 Low Profile 4G SMD Dielectric Antenna

History Handlass

#### Features:

GSM / CDMA / DCS / PCS / WCDMA / UMTS /HSDPA / GPRS / EDGE NB-IoT / CAT M1 Bands 698~960MHz / 1710~2690MHz High Efficiency Multi-Band SMD antenna Low profile 42\*10\*3mm RoHS & REACH Compliant



Introduction	3
Specifications	4
Antenna Characteristics	5
Radiation Patterns	8
Mechanical Drawing - Antenna	12
Antenna Integration Guide	14
Mechanical Drawing – Evaluation Board	21
Solder Reflow Profile	22
Packaging	23
Application Note	24
Changelog	26
	Specifications Antenna Characteristics Radiation Patterns Mechanical Drawing - Antenna Antenna Integration Guide Mechanical Drawing – Evaluation Board Solder Reflow Profile Packaging Application Note

Taoglas makes no warranties based on the accuracy or completeness of the contents of this document and reserves the right to make changes to specifications and product descriptions at any time without notice. Taoglas reserves all rights to this document and the information contained herein.

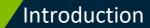
Reproduction, use or disclosure to third parties without express permission is strictly prohibited.

Copyright © Taoglas Ltd.





## 1.





The MCS6.A is a low profile SMD NB-IoT / CAT M1 Bands / 4G/3G/2G embedded antenna designed for direct SMD mount on a device PCB. It provides high efficiency in a very small form factor of just 42\*10\*3mm.

NB-IoT / CAT M1 is a low power wide area (LPWA) technology specifically designed for IoT and M2M. NB-IoT / CAT M1 technology offers lower maintenance cost, with greater efficiency and reliability by reducing power consumption and providing deeper penetration compared to standard cellular technologies. It operates on secure mobile networks making it suited to automotive, smart meter, medical and smart city applications.

If tuning is required, the MCS6.A can be tuned for the device environment without the need for new tooling. Its rectangular shape and very small size make it very easy to integrate. It is supplied on tape and reel ensuring that it can be mounted via pick and place to reflow solder directly on the edge of the PCB board.

This antenna is recommended to be used with longer ground-plane lengths of 120mm or more to attain its highest rated efficiency. Note the Return Loss and Efficiency graphs on Page 16.

Contact your regional Taoglas Customer Support Team for quick and professional support from our senior engineering team on integration and matching of the antenna to your device.



# Specifications

Electrical							
Frequency (MHz)		Band 2		Band 4		Band 12	
		Tx	Rx	Тх	Rx	Тх	Rx
		1850- 1910	1930-1990	1710-1755	2110-2155	699-716	729-746
			Pea	k Gain (dBi)			
On Evalua	ation Board	2.76	3.26	3.11	3.75	-1.05	-0.02
			Avera	age Gain (dB)			
On Evalua	ation Board	-2.04	-1.67	-1.65	-1.85	-3.50	-2.25
			Eff	iciency (%)			
On Evalua	ation Board	62.46	67.47	68.33	65.67	44.58	59.60
			Retu	ırn Loss(dB)			
On Evaluation Board	Typical	<-10	<-10	<-10	<-10	<-10	<-10
On Evaluation Board	Band Edge	<-6	<-6	<-7	<-7	<-5	<-5
Impedance 50Ω							
Polar	Polarization Linear						
Maximum	Input Power		5W				
			Me	chanical			
Antenna I	Dimensions			42mn	n x 10mm x 3mm		
Ma	terial				FR4		
We	eight				2.50g		
Solder	ing Type	SMT through Reflow					
			Envir	ronmental			
Operation <sup>-</sup>	Temperature			-4	10°C ~ +85°C		
Storage To	emperature			-2	10°C ~ +85°C		
Moisture Sensi	tivity Level (MSL)	3 (168 Hours)					

\*All measurements were done on 123\*45mm Evaluation board with 100mm length ground plane.

2.



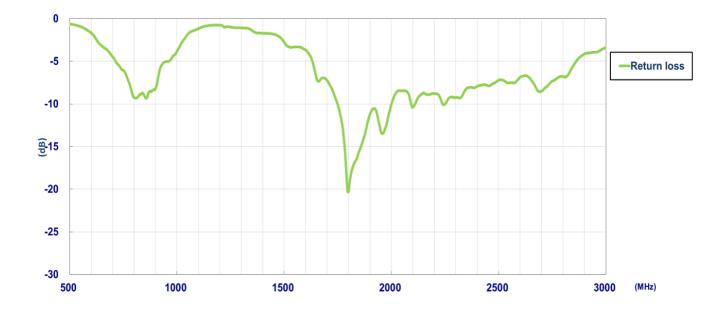
5G/4G Bands				
Band Number	5GNR / FR1 / LTE / LTE-Advanced / WCDMA / HSPA / HSPA+ / TD-SCDMA			
	Uplink	Downlink	Covered	
1	UL: 1920 to 1980	DL: 2110 to 2170	$\checkmark$	
2	UL: 1850 to 1910	DL: 1930 to 1990	$\checkmark$	
3	UL: 1710 to 1785	DL: 1805 to 1880	$\checkmark$	
4	UL: 1710 to 1755	DL: 2110 to 2155	$\checkmark$	
5	UL: 824 to 849	DL: 869 to 894	$\checkmark$	
7	UL: 2500 to 2570	DL:2620 to 2690	$\checkmark$	
8	UL: 880 to 915	DL: 925 to 960	$\checkmark$	
9	UL: 1749.9 to 1784.9	DL: 1844.9 to 1879.9	$\checkmark$	
11	UL: 1427.9 to 1447.9	DL: 1475.9 to 1495.9	$\checkmark$	
12	UL: 699 to 716	DL: 729 to 746	$\checkmark$	
13	UL: 777 to 787	DL: 746 to 756	$\checkmark$	
14	UL: 788 to 798	DL: 758 to 768	$\checkmark$	
17	UL: 704 to 716	DL: 734 to 746 (LTE only)	$\checkmark$	
18	UL: 815 to 830	DL: 860 to 875 (LTE only)	$\checkmark$	
19	UL: 830 to 845	DL: 875 to 890	$\checkmark$	
20	UL: 832 to 862	DL: 791 to 821	$\checkmark$	
21	UL: 1447.9 to 1462.9	DL: 1495.9 to 1510.9	$\checkmark$	
22	UL: 3410 to 3490	DL: 3510 to 3590	$\checkmark$	
23	UL:2000 to 2020	DL: 2180 to 2200 (LTE only)	$\checkmark$	
24	UL:1625.5 to 1660.5	DL: 1525 to 1559 (LTE only)	$\checkmark$	
25	UL: 1850 to 1915	DL: 1930 to 1995	$\checkmark$	
26	UL: 814 to 849	DL: 859 to 894	$\checkmark$	
27	UL: 807 to 824	DL: 852 to 869 (LTE only)	$\checkmark$	
28	UL: 703 to 748	DL: 758 to 803 (LTE only)	$\checkmark$	
29	UL: -	DL: 717 to 728 (LTE only)	$\checkmark$	
30	UL: 2305 to 2315	DL: 2350 to 2360 (LTE only)	×	
31	UL: 452.5 to 457.5	DL: 462.5 to 467.5 (LTE only)	×	
32	UL: -	DL: 1452 - 1496	×	
35		1850 to 1910	$\checkmark$	
38		2570 to 2620	<b>√</b>	
39		1880 to 1920	<b>√</b>	
40		2300 to 2400	×	
41		2496 to 2690	$\checkmark$	
42		3400 to 3600	<b>x</b>	
43		3600 to 3800	×	
48		3550 to 3700	×	
66	UL: 1710-1780	DL: 2110-2200	<b>√</b>	
71		617 to 698	x	
74/75/76		1427 to 1518	x	
78		3300 to 3800	x	
79 *Covered Bands Per	present Efficiency over 20%	4400 to 5000	×	

\*Covered Bands Represent Efficiency over 20%

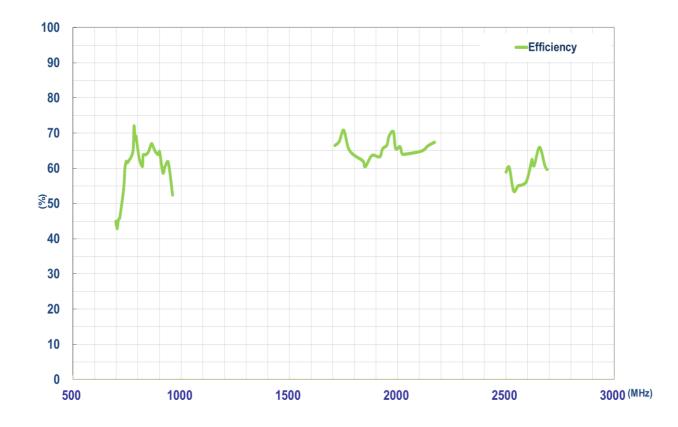




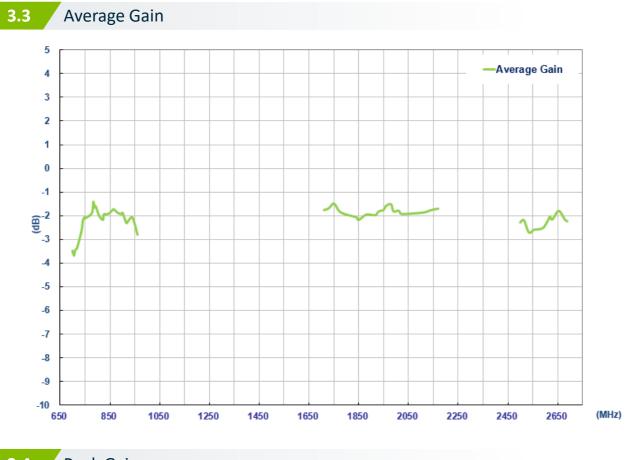


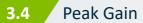


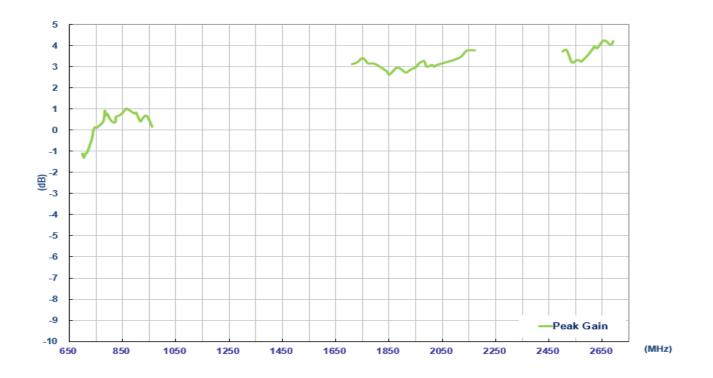
3.2 Efficiency





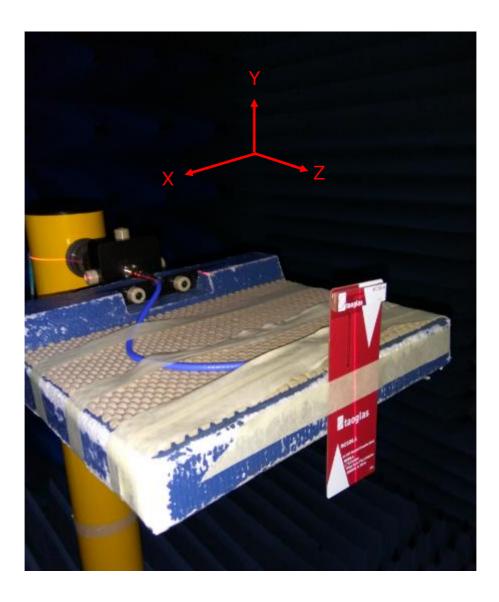








## 4.1 Test Setup

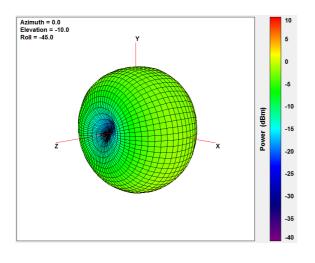


Free space

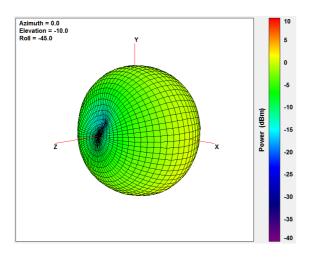


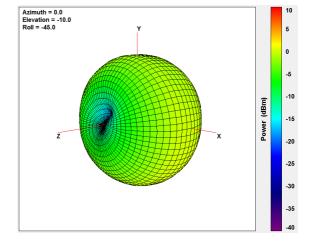


#### 2D & 3D Radiation Patterns

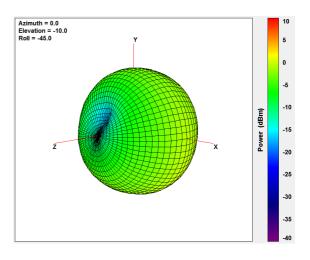


698MHz



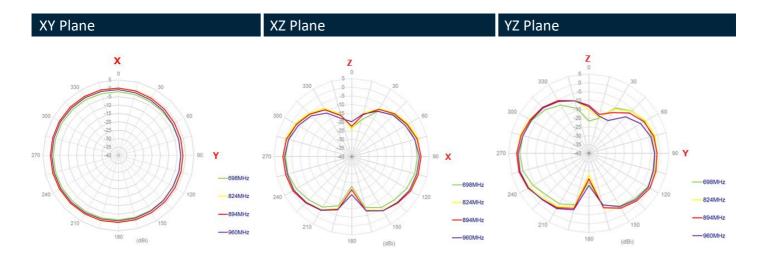


824MHz

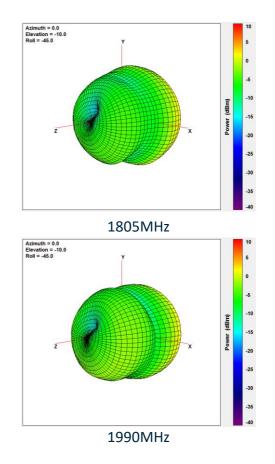


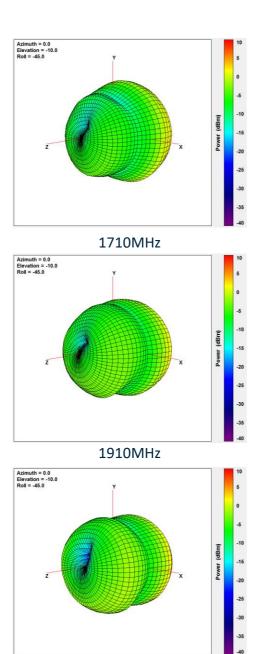
894MHz

960MHz

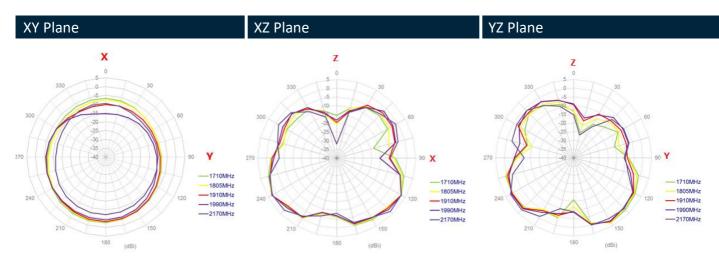




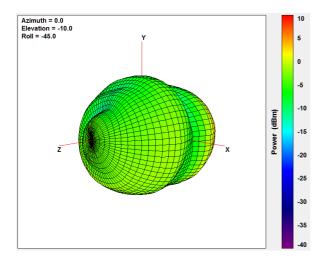




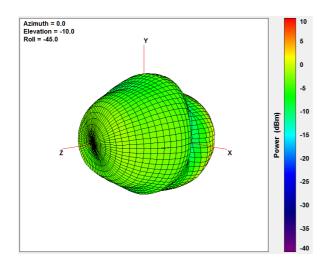


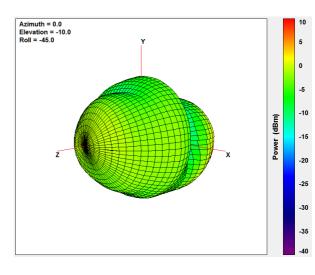






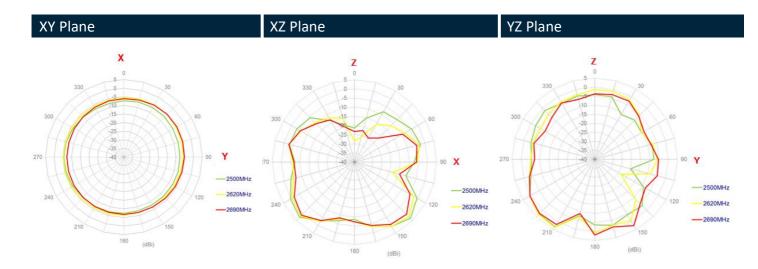
2500MHz



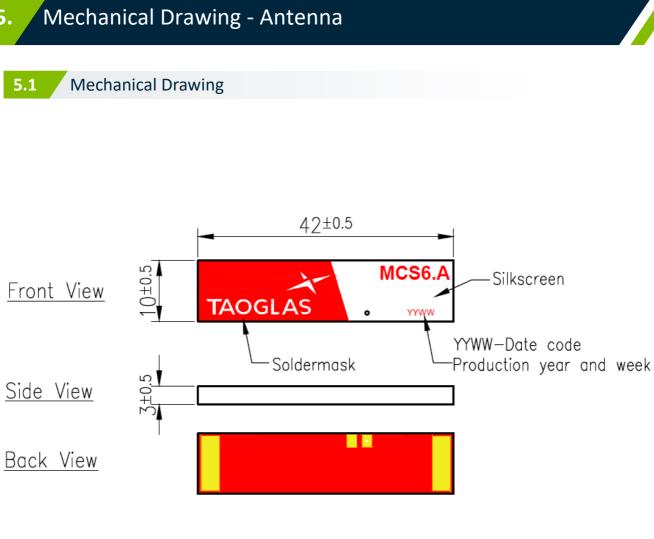


2620MHz

2690MHz

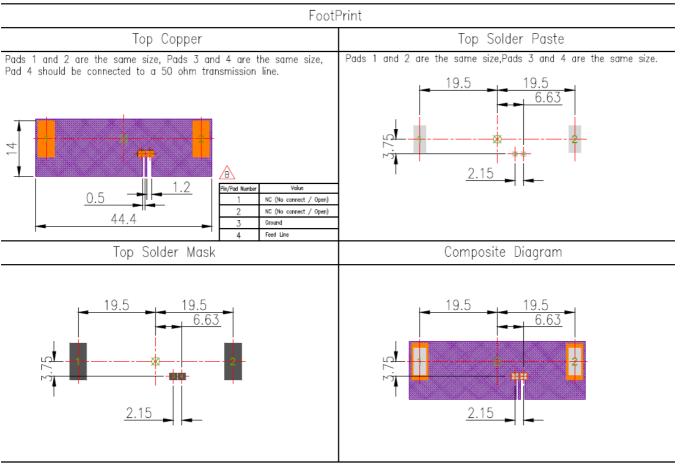








#### 5.2 Footprint



NOTE:

- 1. Au Plated area
- 2. Solder Mask area
- 3. Copper area
- 4. Paste area
- 5. Keepout Region area
- Silkscreen
  Soldermask
- 8. Ground keepout should extend through any inner PCB layers and any sides around the antenna till the board edge to minimize coupling from RF feed to ground, except the side facing system ground.
- 9. Any vias in pads should be either filled or tented to prevent solder from wicking away from the pad during reflow.
- 10. The dimension tolerances should follow standard PCB manufacturing guidelines.



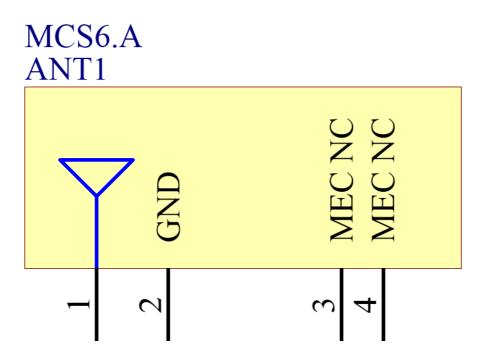




## 6.1 Schematic Symbol and Pin Definition

The circuit symbol for the antenna is shown below. The antenna has 4 pins with only two pins (Pin 1 and Pin 2) as functional. Pins 3 and 4 are for mechanical strength.

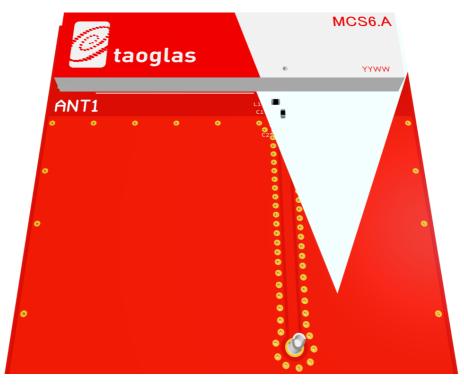
Pin	Description
1	RF Feed
2	Ground
3,4	Mechanical, Not Connected





#### 6.2 Antenna Integration

For any given PCB size, the antenna should ideally be placed on the PCB's longest side, to take advantage of the ground plane. Optimized matching components can be placed as shown.



Top Side w/ Solder Mask

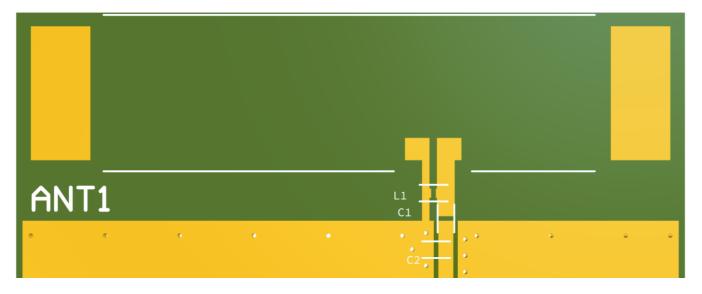


Top Side w/o Solder Mask



#### 6.3 PCB Layout

The footprint and clearance on the PCB must meet the layout drawing in (Footprint Drawing). Note the placement of the optimized components. L1 is placed as close as possible to the RF feed (pad 1) but still within the transmission line. C1 is then placed tightly in series after that. C2 is an optional component but the footprint is recommended in case it is needed.



Topside

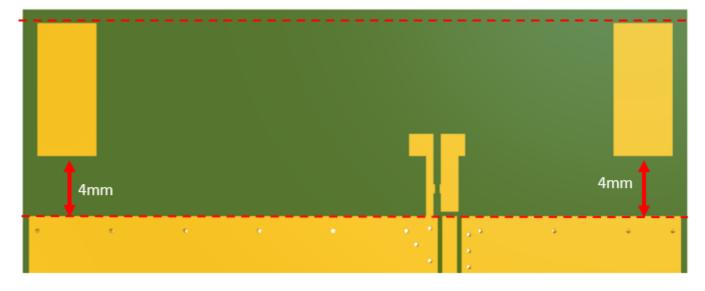


Bottom Side

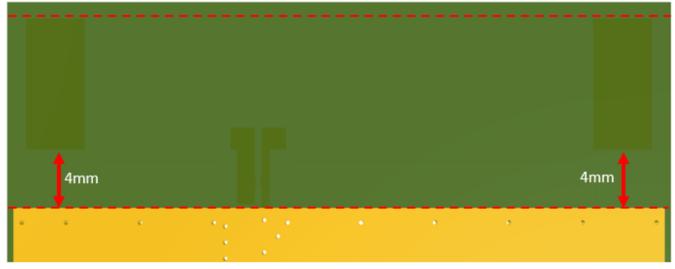


#### 6.4 PCB Clearance

Below shows the antenna footprint and clearance through ALL layers on the PCB. Only the antenna pads and connections to feed and GND are present within this clearance area (marked RED). The clearance area extends to 2.8mm in length & 10.6mm in width from the centre of the PCB. This clearance area includes the bottom side and ALL internal layers on the PCB.



Topside

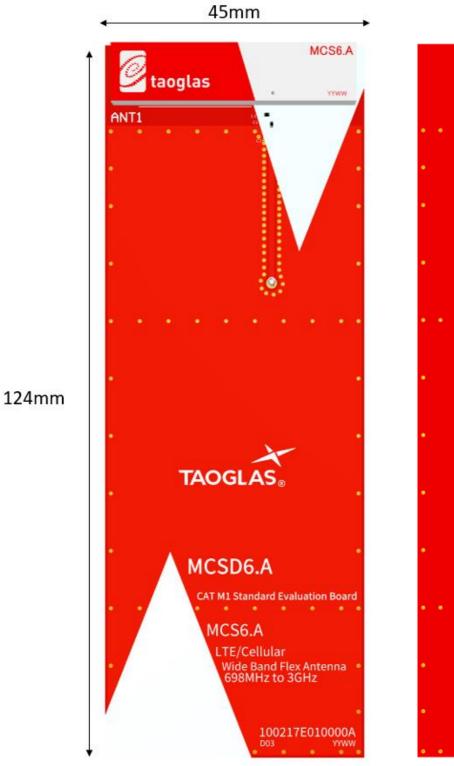


**Bottom Side** 



#### Evaluation Board

6.5



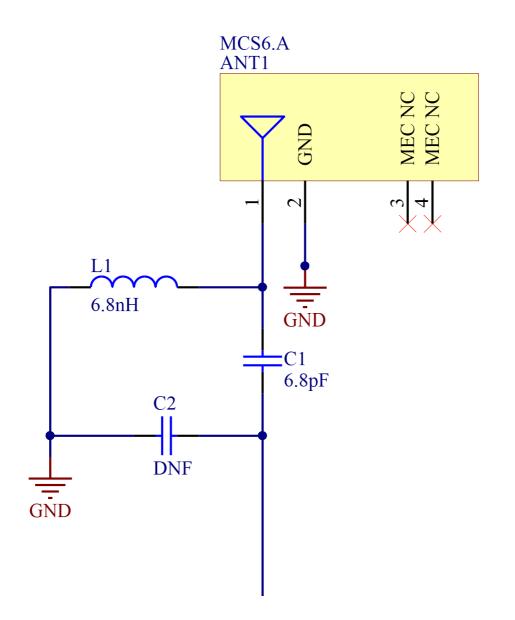
Topside

Bottom Side



#### 6.6 Evaluation Board Matching Circuit

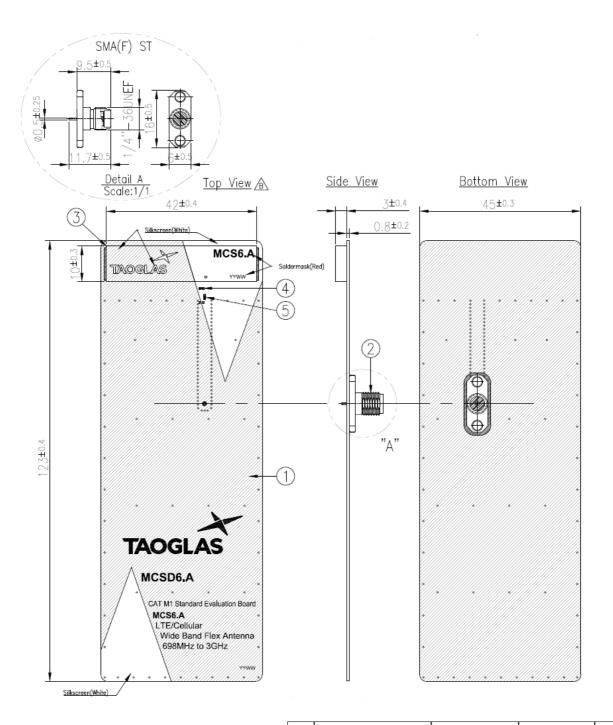
A matching component (L1) in parallel with the MCS6.A is required for the antenna to have optimal performance on the evaluation board, located outside of the ground plane in the space specified in the above images. Additional matching components may be necessary for your device, so we recommend incorporating extra component footprints, forming a "pi" network, between the cellular module and the edge of the ground



Designator	Туре	Value	Manufacturer	Manufacturer Part Number
L1	Inductor	6.8nH	TDK	MLK1005S6N8DT000
C1	Capacitor	6.8pF	Murata	GRM1555C1H6R8CA01D
C2	Capacitor	Not Fitted	-	-

TAOGLAS.

# Mechanical Drawing – Evaluation Board



#### Note:

- 1. Week Batch Code
- Example: 2013 Week 10=1310 2. Soldered area
- 3. Soldermask area(Red)
- A Silkscreen · White
- 4. Silkscreen : White

	Name	P/N	Material	Finish	QTY
1	MCSD6.A EVB PCB	100217 <b>E</b> 010000A	Composite 0.8t	Red	1
2	SMA(F) ST PCB	200413B000002A	Brass	Au Plated	1
3	MCS6.A PCB Antenna	100217E020000A	Composite 3t	Red	1
4	6.8nH Inductor (0402)	001513A000055A	Ceramic	N/A	1
5	6.8pF Capacitor (0402)	001512 <b>I</b> 000055A	Ceramic	N/A	1

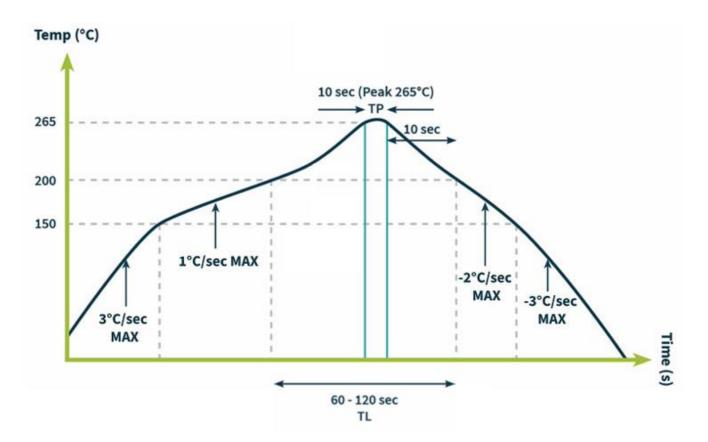
7.



## Solder Reflow Profile

8.

The MCS6.A can be assembled by following the recommended soldering temperatures are as follows:



Smaller components are typically mounted on the first pass, however, we do advise mounting the MCS6.A when placing larger components on the board during subsequent reflows.

Note: Soldering flux classified ROL0 under IPC J-STD-004 is recommended.



## 9. Packaging

1000 pcs MCS6.A reel Dimensions - 330\*330\*60mm Weight - 2kg

1000 pcs MCS6.A / 1 Reel in small box Dimensions - 335\*340\*90mm Weight - 2.1Kg

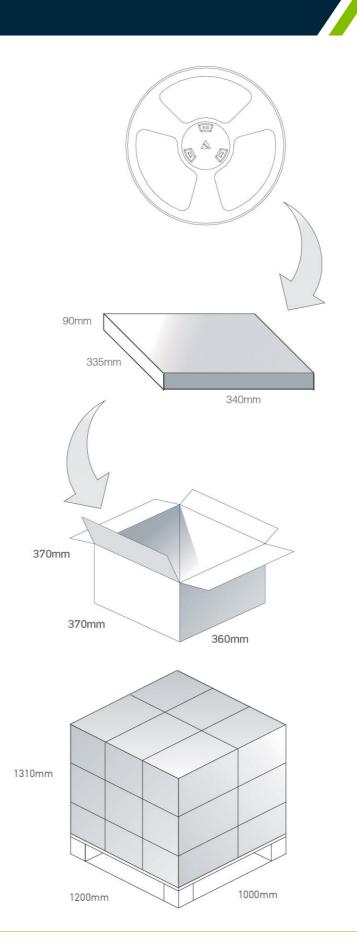
4 reels, 4000 pcs in one carton Carton Dimensions - 370\*360\*370mm Weight - 9.2Kg

Pallet Dimensions 1200\*1000\*1310mm

18 Cartons per Pallet

6 Cartons per layer

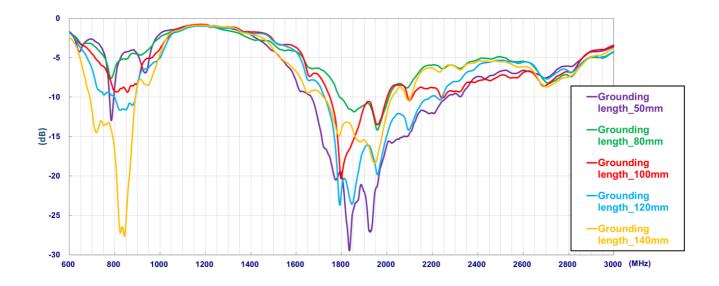
3 Layers

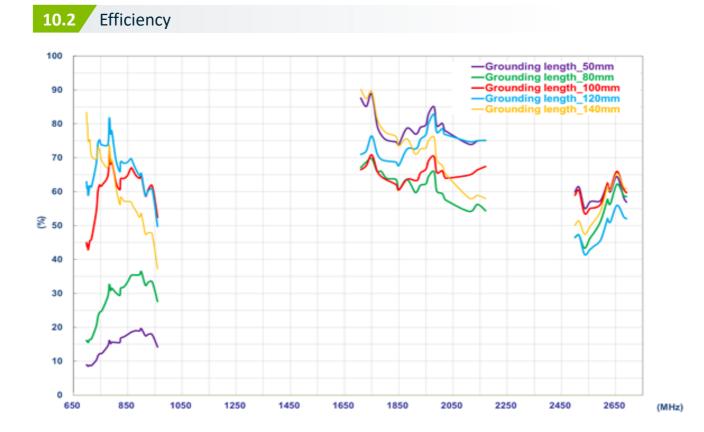




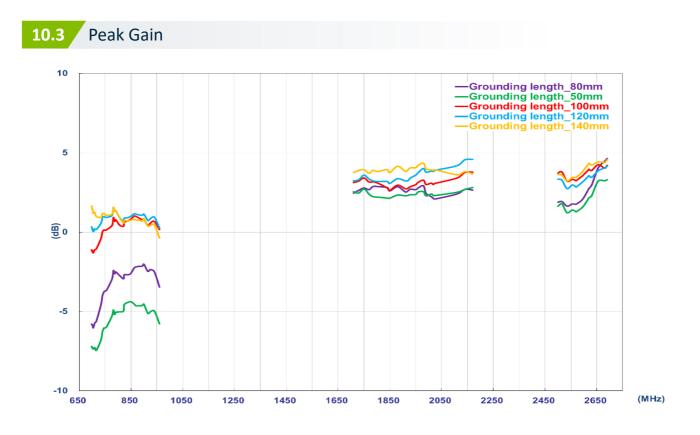
# **10.** Application Note





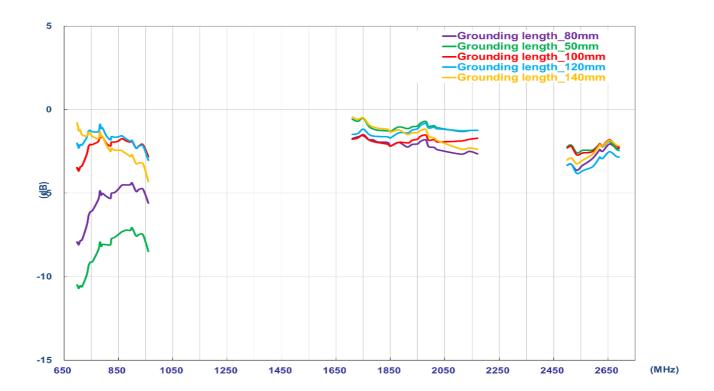














Changelog for the datasheet			
SPE-17-8-036 – MCS6.A			
Revision: G (Current	t Version)		
Date:	2023-10-31		
Changes:	Added Solder Reflow Profile		
Changes Made by:	Cesar Sousa		

#### **Previous Revisions**

Revision: F	
Date:	2023-03-13
Changes:	Antenna Integration Guide Added
Changes Made by:	Cesar Sousa

Revision: E	
Date:	2021-09-14
Changes:	MSL, font and datasheet rev as it was listed as the "B" version.
Changes Made by:	Erik Landi

Revision: D			
Date:	2019-07-25		
Changes:	Template & EVB Drawing		
Changes Made by:	Jack Conroy		

Revision: C	
Date:	2018-10-23
Changes:	Pads Amended
Changes Made by:	David Connolly

Revision: B		
Date:	2017-08-08	
Changes:	Drawing Updated	
Changes Made by:	Andy Mahoney	



# www.taoglas.com